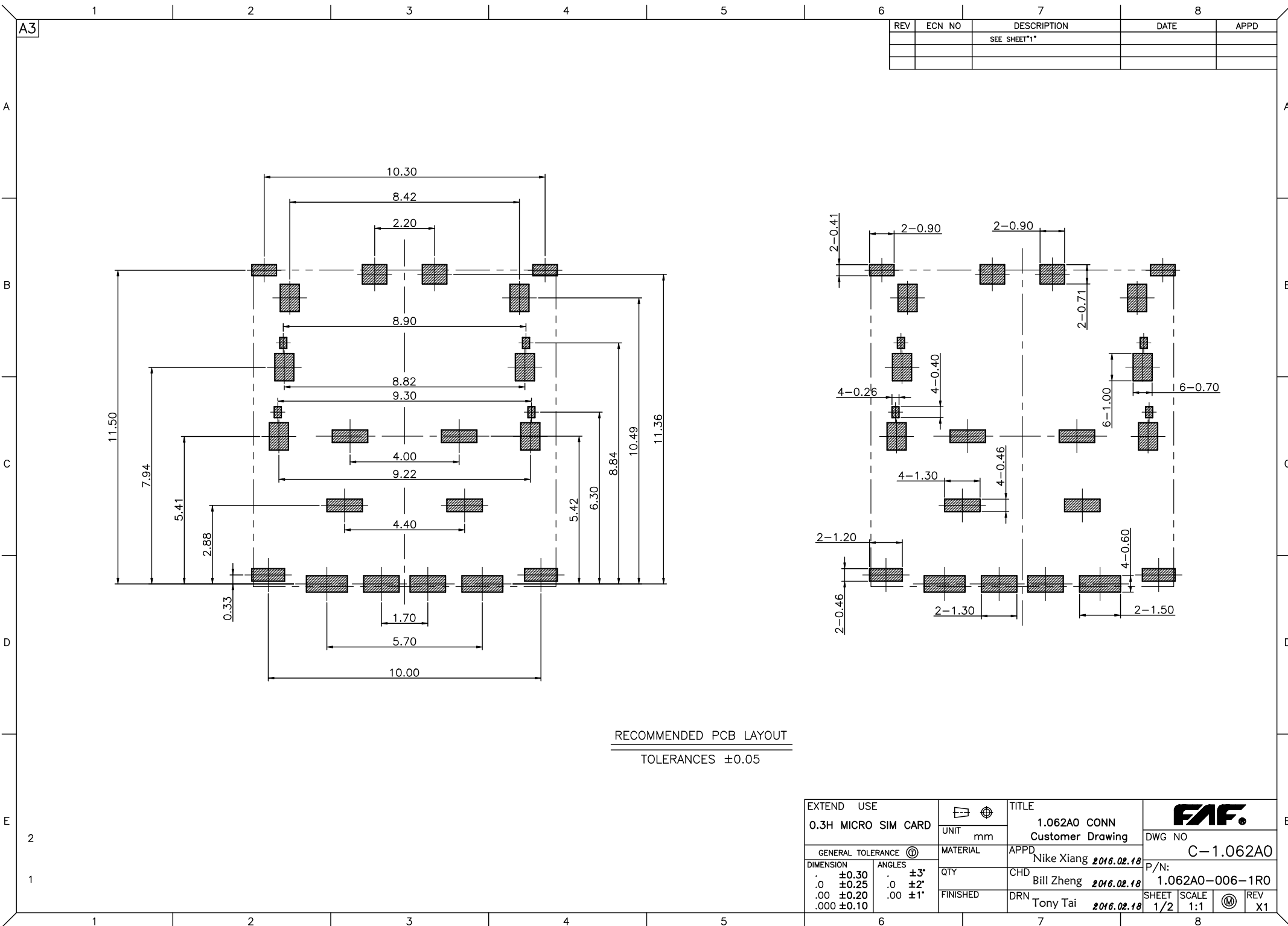


REV	ECN NO	DESCRIPTION	DATE	APPD
X1		INITIAL RELEASE	2016.02.18	

- NOTE:
- MATERIALS:
 - 1.1 HOUSING: THERMOPLASTIC, LCP S475, UL94 V-0, COLOR: BLACK;
 - 1.2 TERMINAL: COPPER ALLOY C17200-190 XHM/C17200-190 XHMB, T=0.06±0.01;
 - FINISH:
 - 2.1 TERMINAL: 15u" Min. GOLD PLATING ON CONTACT AREA, GOLD FLASH PLATED ON SOLDERING TAIL, 50u" Min. NICKEL UNDER PLATING OVERALL;

EXTEND USE	UNIT		TITLE		DWG NO	
0.3H MICRO SIM CARD	mm		1.062A0 CONN Customer Drawing		C-1.062A0	
GENERAL TOLERANCE	MATERIAL	APPD	P/N:			
DIMENSION	QTY	CHD	1.062A0-006-1R0			
FINISHED	DRN	SHEET		SCALE	REV	
		1/2	1:1	X1		





RECOMMENDED PCB LAYOUT
TOLERANCES ±0.05

REV	ECN NO	DESCRIPTION	DATE	APPD
		SEE SHEET*1*		

EXTEND USE				TITLE			
0.3H MICRO SIM CARD		UNIT mm		1.062A0 CONN		DWG NO	
GENERAL TOLERANCE Ⓢ		MATERIAL		APPD Nike Xiang 2016.02.18		C-1.062A0	
DIMENSION		ANGLES		CHD Bill Zheng 2016.02.18		P/N: 1.062A0-006-1R0	
. ±0.30	. ±3°	QTY		DRN Tony Tai 2016.02.18		SHEET SCALE	
.0 ±0.25	.0 ±2°	FINISHED		1/2		1:1	
.00 ±0.20	.00 ±1°			REV		X1	
.000 ±0.10							